

Ming-Tzer Lin

List of Publications by Year in descending order

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48
papers

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all docs

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docs citations

48
times ranked

450
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|---|-----|-----------|
| 1 | The Effects of Stresses and Interfaces on Texture Transformation in Silver Thin Films. <i>Nanomaterials</i> , 2022, 12, 329. | 4.1 | 4 |
| 2 | A study of the phase transformation of low temperature deposited tantalum thin films using high power impulse magnetron sputtering and pulsed DC magnetron sputtering. <i>Surface and Coatings Technology</i> , 2022, 436, 128288. | 4.8 | 7 |
| 3 | Mechanical Properties and Residual Stress Measurement of TiN/Ti Duplex Coating Using HiPIMS TiN on Cold Spray Ti. <i>Coatings</i> , 2022, 12, 759. | 2.6 | 4 |
| 4 | Size Effects in Internal Friction of Nanocrystalline Aluminum Films. <i>Materials</i> , 2021, 14, 3401. | 2.9 | 2 |
| 5 | Use of Digital Image Correlation Method to Measure Bio-Tissue Deformation. <i>Coatings</i> , 2021, 11, 924. | 2.6 | 5 |
| 6 | Measurement of Effects of Different Substrates on the Mechanical Properties of Submicron Titanium Nickel Shape Memory Alloy Thin Film Using the Bulge Test. <i>Micromachines</i> , 2021, 12, 85. | 2.9 | 2 |
| 7 | Study on Electromigration Effects and IMC Formation on Cu-Sn Films Due to Current Stress and Temperature. <i>Applied Sciences (Switzerland)</i> , 2020, 10, 8893. | 2.5 | 3 |
| 8 | Using Digital Image Correlation on SEM Images of Strain Field after Ion Beam Milling for the Residual Stress Measurement of Thin Films. <i>Materials</i> , 2020, 13, 1291. | 2.9 | 6 |
| 9 | <i>Ab-Initio</i> Study of (111) to (001) Texture Transformation in Ag Thin Films. <i>Materials Transactions</i> , 2019, 60, 437-440. | 1.2 | 1 |
| 10 | Design of fins with a grooved heat pipe for dissipation of heat from high-powered automotive LED headlights. <i>Energy Conversion and Management</i> , 2019, 180, 550-558. | 9.2 | 52 |
| 11 | Digital Image Correlation on FIB Ring-Core Measurement on Residual Stress of Thin Films. The Abstracts of ATEM International Conference on Advanced Technology in Experimental Mechanics Asian Conference on Experimental Mechanics, 2019, 2019, 1008B1145. | 0.0 | 0 |
| 12 | Effects of Electrical Current and External Stress on the Electromigration of Intermetallic Compounds Between the Flip-Chip Solder and Copper Substrate. <i>Journal of Electronic Materials</i> , 2018, 47, 35-48. | 2.2 | 14 |
| 13 | Digital image correlation of SEM images for surface deformation of CMOS IC. <i>Microelectronic Engineering</i> , 2018, 201, 16-21. | 2.4 | 7 |
| 14 | Time and temperature dependent mechanical behavior of Al/Ti thin films application for MEMS. , 2017, , . | | 2 |
| 15 | Using Taguchi method to obtain the optimal design of heat dissipation mechanism for electronic component packaging. <i>Microelectronics Reliability</i> , 2016, 65, 131-141. | 1.7 | 3 |
| 16 | Viscoelastic mechanical properties measurement of thin Al and Al-Mg films using bulge testing. <i>Thin Solid Films</i> , 2016, 618, 2-7. | 1.8 | 18 |
| 17 | Simulation of a high-power LED lamp for the evaluation and design of heat dissipation mechanisms. <i>Microsystem Technologies</i> , 2016, 22, 523-529. | 2.0 | 4 |
| 18 | Driving forces for texture transformation in thin Ag films. <i>Acta Materialia</i> , 2016, 105, 495-504. | 7.9 | 20 |

| # | ARTICLE | IF | CITATIONS |
|----|---|-----|-----------|
| 19 | Effect of Loading Stress on the Growth of Cu/Sn Intermetallic Compounds at High Temperatures. Journal of Electronic Materials, 2015, 44, 604-611. | 2.2 | 7 |
| 20 | In Situ Energy Loss and Internal Friction Measurement of Nanocrystalline Copper Thin Films Under Different Temperature. Conference Proceedings of the Society for Experimental Mechanics, 2015, , 67-73. | 0.5 | 0 |
| 21 | Recent Development of Using Optical Methods to Measure the Mechanical Properties of Thin Films. , 2014, , . | | 0 |
| 22 | Effect of temperature on energy loss and internal friction in nanocrystalline copper thin films. Surface and Coatings Technology, 2014, 260, 272-278. | 4.8 | 8 |
| 23 | Constructing high-power LED lamp model to evaluate different heat dissipation mechanism design. , 2014, , . | | 1 |
| 24 | Evaluating heat dissipation in edge-lit LED backlight module using Taguchi method. , 2014, , . | | 1 |
| 25 | The study of internal friction in nanocrystalline Ag and Au thin films. Thin Solid Films, 2014, 570, 262-267. | 1.8 | 6 |
| 26 | Planar copper-tin inter-metallic film formation on strained substrates. Microelectronics Reliability, 2014, 54, 1378-1383. | 1.7 | 1 |
| 27 | Cyclic creep and fatigue testing of nanocrystalline copper thin films. Surface and Coatings Technology, 2013, 215, 393-399. | 4.8 | 15 |
| 28 | Novel full range vacuum pressure sensing technique using free decay of trapezoid micro-cantilever beam deflected by electrostatic force. Microsystem Technologies, 2012, 18, 1903-1908. | 2.0 | 10 |
| 29 | Linear energy control of laser drilling and its application in the repair of TFT-LCD bright pixels. Microsystem Technologies, 2012, 18, 1909-1915. | 2.0 | 1 |
| 30 | Influence of External Strain on the Growth of Interfacial Intermetallic Compounds Between Sn and Cu Substrates. Journal of Electronic Materials, 2012, 41, 3309-3319. | 2.2 | 2 |
| 31 | Heat dissipation design and analysis of high power LED array using the finite element method. Microelectronics Reliability, 2012, 52, 905-911. | 1.7 | 131 |
| 32 | Enhanced growth of the Ni ₃ Sn ₄ phase at the Sn/Ni interface subjected to strains. Scripta Materialia, 2011, 65, 691-694. | 5.2 | 19 |
| 33 | The thermal evaluation of the substrate mixed with microencapsulated phase change materials for MEMS packaging applications. Microsystem Technologies, 2011, 17, 693-699. | 2.0 | 8 |
| 34 | Measurement of static and dynamic mechanical behavior of micro and nano-scale thin metal films: using micro-cantilever beam deflection. Microsystem Technologies, 2011, 17, 721-730. | 2.0 | 6 |
| 35 | OS06-2-2 Thickness dependence of the internal frictions in aluminum thin film. The Abstracts of ATEM International Conference on Advanced Technology in Experimental Mechanics Asian Conference on Experimental Mechanics, 2011, 2011.10, _OS06-2-2-. | 0.0 | 0 |
| 36 | Optical micro-paddle beam deflection measurement for electrostatic mechanical testing of nano-scale thin film application to MEMS. Microsystem Technologies, 2010, 16, 1131-1137. | 2.0 | 17 |

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|----|---|-----|-----------|
| 37 | Novel heat dissipation design for light emitting diode applications. <i>Microsystem Technologies</i> , 2010, 16, 519-526. | 2.0 | 5 |
| 38 | Novel Microtensile Method for Monotonic and Cyclic Testing of Freestanding Copper Thin Films. <i>Experimental Mechanics</i> , 2010, 50, 55-64. | 2.0 | 21 |
| 39 | Three-Phase Linear Motor Heat Transfer Analysis Using the Finite-Element Method. <i>Heat Transfer Engineering</i> , 2010, 31, 617-624. | 1.9 | 6 |
| 40 | Design and development of a novel paddle test structure for the mechanical behavior measurement of thin films application for MEMS. <i>Microsystem Technologies</i> , 2009, 15, 1207-1216. | 2.0 | 13 |
| 41 | Monotonic and fatigue testing of freestanding submicron thin beams application for MEMS. <i>Microsystem Technologies</i> , 2008, 14, 1041-1048. | 2.0 | 10 |
| 42 | Process nano scale mechanical properties measurement of thin metal films using a novel paddle cantilever test structure. , 2008, , . | | 0 |
| 43 | Mechanical property measurement of nano-scale metal films on the novel paddle cantilever beams using four step phase-shifting method. , 2008, , . | | 1 |
| 44 | The influence of vanadium alloying on the elevated-temperature mechanical properties of thin gold films. <i>Thin Solid Films</i> , 2007, 515, 7919-7925. | 1.8 | 10 |
| 45 | Design and development of sub-micron scale specimens with electroplated structures for the microtensile testing of thin films. <i>Microsystem Technologies</i> , 2007, 13, 1559-1565. | 2.0 | 7 |
| 46 | OS5-2-5 Micro scale monotonic and tension fatigue testing of spring-bridge freestanding thin films application for MEMS. The Abstracts of ATEM International Conference on Advanced Technology in Experimental Mechanics Asian Conference on Experimental Mechanics, 2007, 2007.6, _OS5-2-5-1- OS5-2-5-6. | 0.0 | 0 |
| 47 | Temperature-dependent microtensile testing of thin film materials for application to microelectromechanical system. <i>Microsystem Technologies</i> , 2006, 12, 1045-1051. | 2.0 | 25 |
| 48 | Design an Electroplated Frame Freestanding Specimen for Microtensile Testing of Submicron thin TaN and Cu Film. <i>Materials Research Society Symposia Proceedings</i> , 2006, 914, 1. | 0.1 | 4 |